

AMENDMENTS TO THE CLAIMS

1. – 6. (Cancelled)

7. (Previously Amended) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad.

8. (Currently Amended) The suspension as claimed ~~claim~~ in claim 7, wherein said bonding substance is solder.

9. (Currently Amended) The suspension as claimed ~~claim~~ in claim 7, wherein said bonding substance is a conductive polymer.

10. (Currently Amended) The suspension as claimed ~~claim~~ in claim 7, wherein said bonding substance is an adhesive.

11. (Currently Amended) The suspension as claimed ~~claim~~ in claim 7, wherein said bonding substance is a film.

12. (Currently Amended) The suspension as claimed ~~claim~~ in claim 8, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .